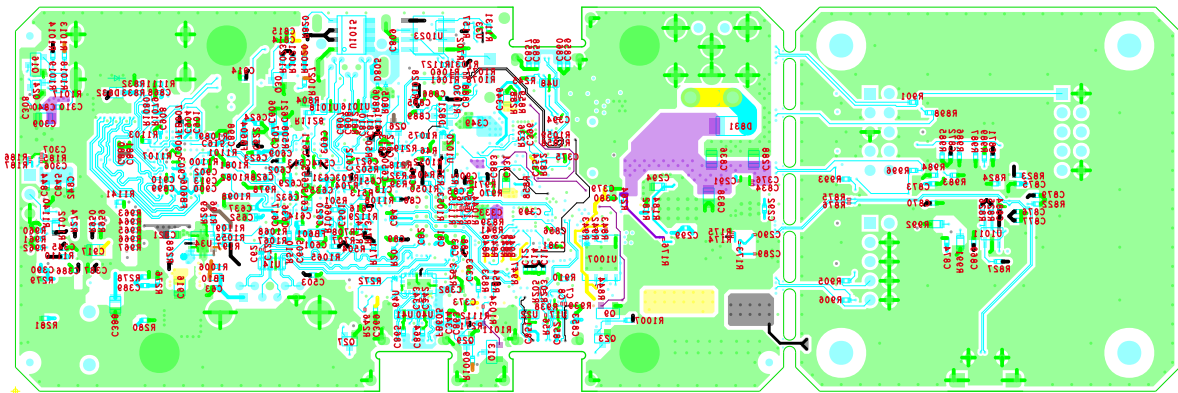
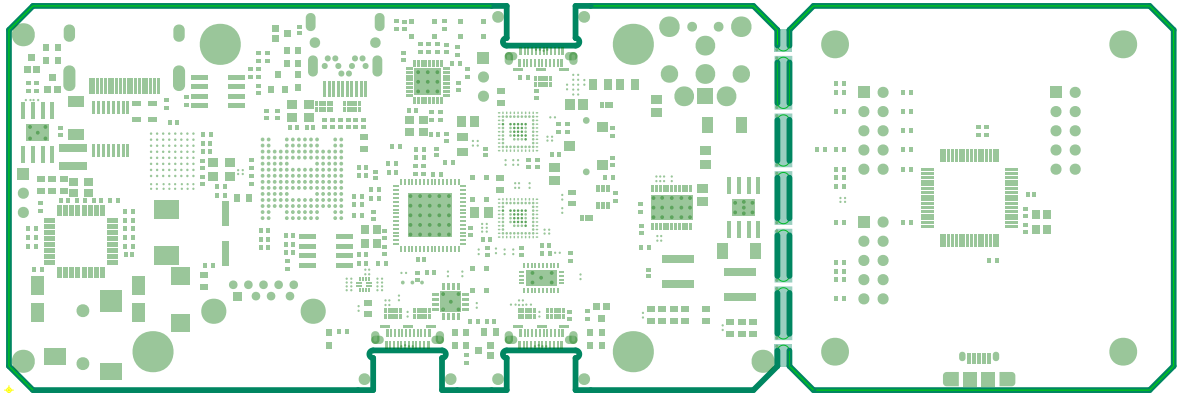


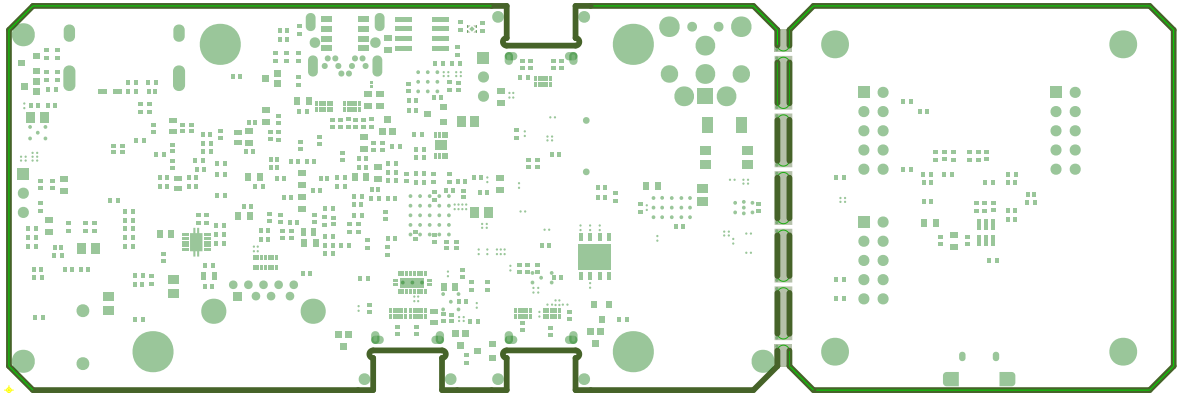
BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: LAYER 1 - TOP SIDE	



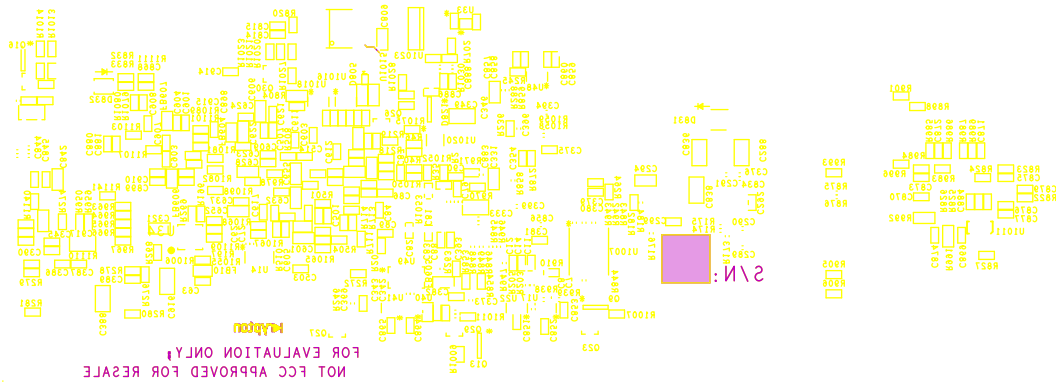
BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: LAYER 10 - BOTTOM SIDE	



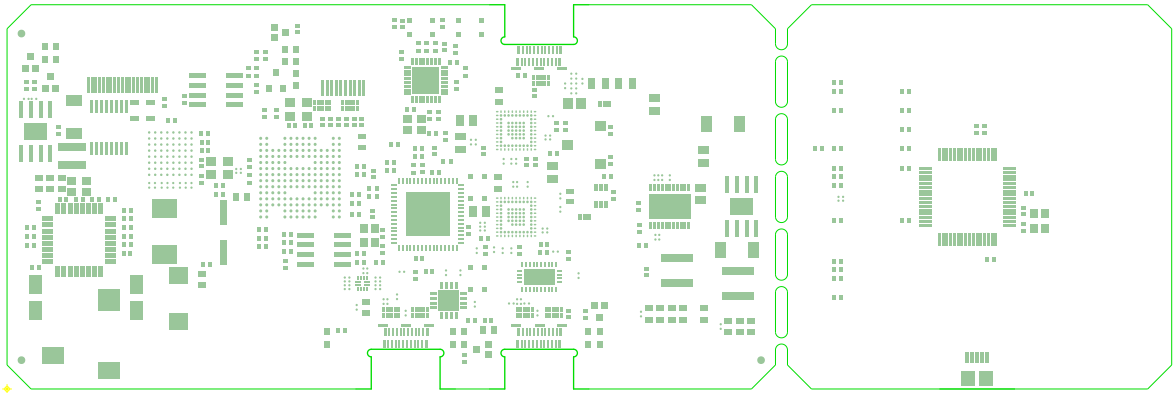
BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: SOLDERMASK TOP		



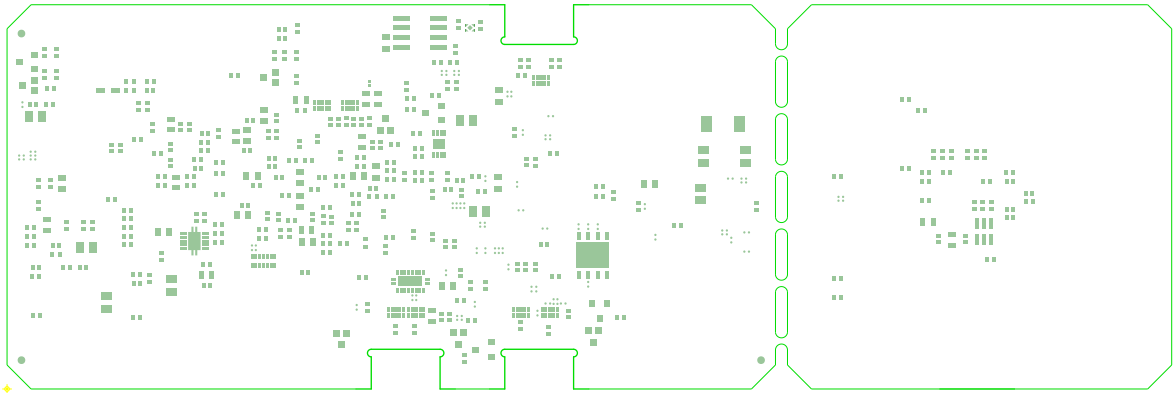
BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: SOLDERMASK BOTTOM	



BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: SILKSCREEN BOTTOM	



BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: PASTEMASK TOP	



BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: PASTEMASK BOTTOM	

8 7 6 5 4 3 2 1

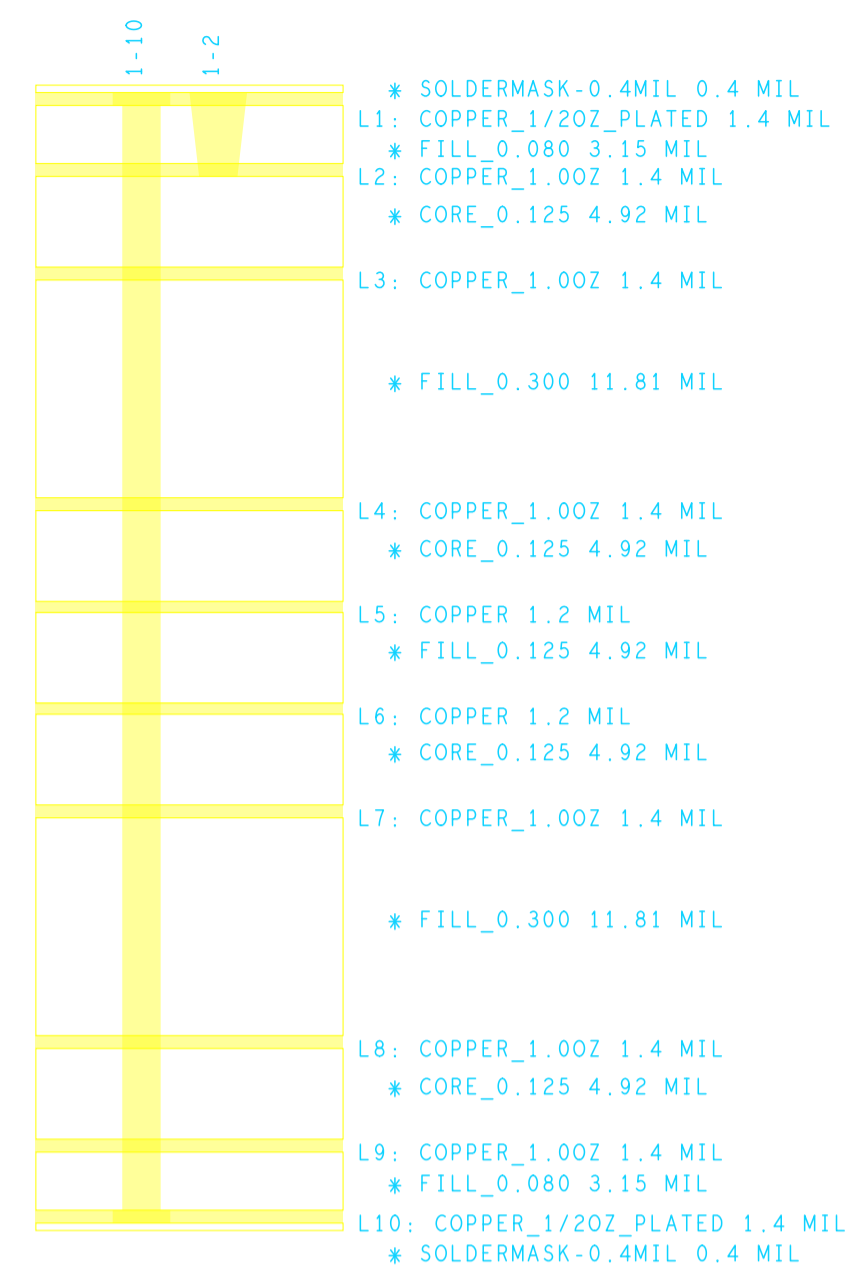


TABLE 1:

LAYER NO.	LAYER NAME	DIFFERENTIAL PAIR IMPEDANCE (OHMS)	DIFF TRACE WIDTH	DIFF TRACE SPACING	SINGLE ENDED IMPEDANCE (OHMS)	SINGLE ENDED TRACE WIDTH	REFERENCE LAYER
LAYER 1	TOP	100 +/- 10% 85 +/- 10%	0.006" 0.004"	0.0050" 0.0050"	50 +/- 10%	0.0045"	LAYER 3 LAYER 2
LAYER 2	L2_GND						
LAYER 3	L3_SIG	85 +/- 10%	0.0045"	0.005"	50 +/- 10%	0.005"	LAYER 2
LAYER 4	L4_3P3V						
LAYER 5	L5_VBUS_GND						
LAYER 6	L6_1P2V_GND						
LAYER 7	L7_5V						
LAYER 8	L8_SIG	85 +/- 10%	0.0045"	0.005"	50 +/- 10%	0.005"	LAYER 9
LAYER 9	L9_GND						
LAYER 10	BOTTOM	100 +/- 10% 85 +/- 10%	0.006" 0.004"	0.0050" 0.0050"	50 +/- 10%	0.0045"	LAYER 8 LAYER 9

SPECIAL FAB NOTES:

- 2: ALL 6.01 MIL VIAS NEED TO BE FILLED USING NON-CONDUCTIVE EPOXY AND PLATED SMOOTH (TOP SIDE ONLY).
- 3: ALL 8 MIL VIAS TO BE TENTED ON BOTH SIDES.

DRILL CHART: TOP to L2
ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
-	6.01	+3.0/-6.0	PLATED	46

DRILL CHART: TOP to BOTTOM
ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
-	8.0	+3.0/-8.0	PLATED	1507
-	10.0	+3.0/-10.0	PLATED	74
-	19.69	+3.0/-3.0	PLATED	10
-	25.59	+1.97/-1.97	PLATED	6
+	28.0	+3.0/-3.0	PLATED	9
o	38.0	+3.0/-3.0	PLATED	37
+	51.0	+3.0/-3.0	PLATED	2
+	63.0	+3.0/-3.0	PLATED	4
o	67.0	+3.0/-3.0	PLATED	2
o	91.0	+3.0/-3.0	PLATED	2
@	125.0	+2.0/-2.0	PLATED	4
-	12.0	+2.0/-2.0	NON-PLATED	12
-	35.0	+2.0/-2.0	NON-PLATED	2
L	51.0	+2.0/-2.0	NON-PLATED	2
o	55.0	+2.0/-2.0	NON-PLATED	2
T	67.0	+2.0/-2.0	NON-PLATED	2
G	125.0	+2.0/-2.0	NON-PLATED	4
+	33.46x25.59	+3.15/-3.15	PLATED	2
+	43.11x19.69	+1.97/-1.97	PLATED	6
+	43.31x19.69	+1.97/-1.97	PLATED	6
o	59.06x32.48	+3.15/-3.15	PLATED	2
o	66.93x35.43	+3.15/-3.15	PLATED	2
o	70.87x27.56	+3.15/-3.14.96	PLATED	2
o	86.61x27.56	+3.94/-3.94	PLATED	2
o	106.3x35.43	+1.97/-1.97	PLATED	2

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 NUMBER OF LAYERS: 10
 MIN. TRACK WIDTH: 4.0 MIL
 MIN. CLEARANCE: 3.9 MIL
 MIN. VIA PAD/DRILL: 12.0/6.0 MIL (BLIND)

MIN. ANNULAR RING 2 MIL EXTERNAL PER IPC-6012C CLASS 2
 REGISTRATION TOLERANCES: METAL +/- X MIL, HOLES +/- X MIL

IMPEDANCE CONTROL: NONE YES - SEE TABLE 1

MIXED DIELECTRIC: NO YES

LAMINATE MATERIAL:
 FR-4 HIGH Tg ROGERS 4350B OTHER: _____

THICKNESS:
 0.069" +/-10% 0.093" +/-10% OTHER: _____

TOLERANCE: IPC-6012C TYPE 3 CLASS 2 BOW & TWIST: IPC-6012C TYPE 3 CLASS 2

OTHER +/- OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.

INNER SIGNAL: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.

INNER PLANE: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.

OTHER: _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM

SILKSCREEN COLOR: WHITE OTHER _____

SOLDERMASK: (PER IPC-6011,6012)
 TOP BOTTOM

SOLDERMASK COLOR: GREEN BLUE OTHER: BLACK

THROUGH-HOLE VIA TREATMENT:
 OPEN TENTED IDENTIFIER: ALL 8 MIL VIAS

VIA FILL USING NON-CONDUCTIVE EPOXY:
 NO YES IDENTIFIER: ALL 6.01 MIL VIAS

THEIVING ALLOWED: YES NO

BOARD SURFACE TREATMENT:
 NICKEL/GOLD (ENIG) ORGANIC (OSP) HASL ENEPIG

IMMERSION TIN OTHER _____

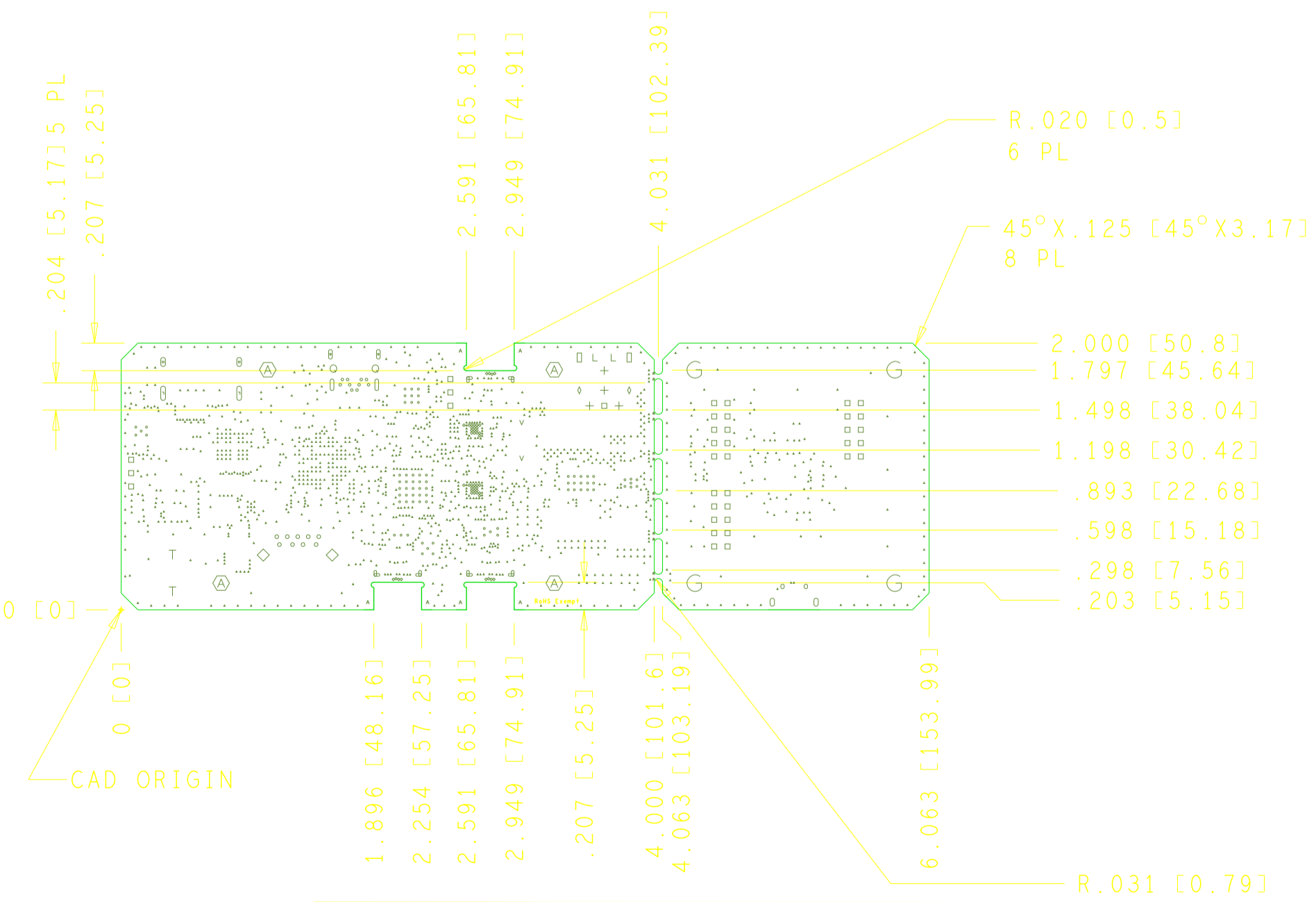
FOR WIRE BONDING:
 HARD GOLD SOFT GOLD PER SUPPLIED ARTWORK

ADDITIONAL REQUIREMENTS:
 MICRO-SECTION TDR REPORTS/COUPONS ELECTRICAL TEST

CERTIFICATES OF COMPLIANCE RoHS UL 94V-0

VENDOR MARKING:
 VENDOR DATE CODE, UL, LOGO: ETCH SILKSCREEN BREAK-AWAY

IN AN OPEN AREA WHERE INDICATED (SEE DRAWING)



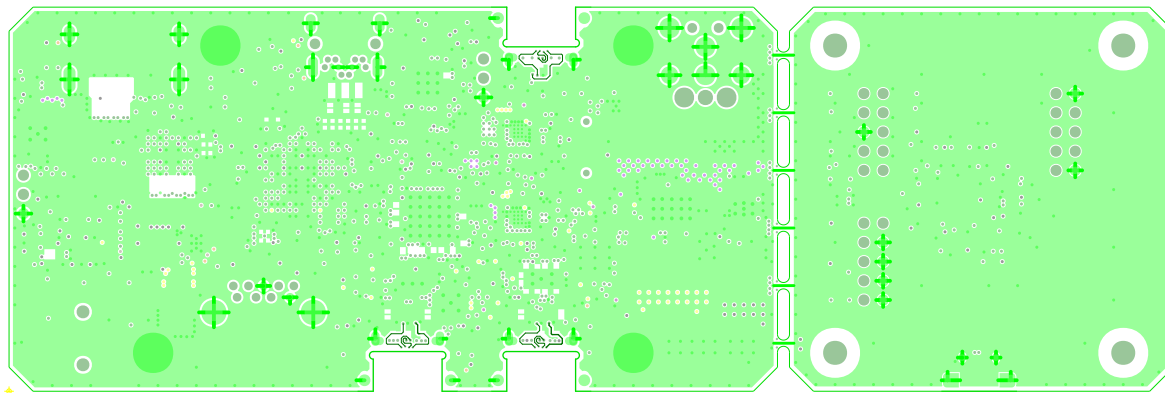
BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: FABRICATION DRAWING	

KRYPTON SOLUTIONS CONFIDENTIAL

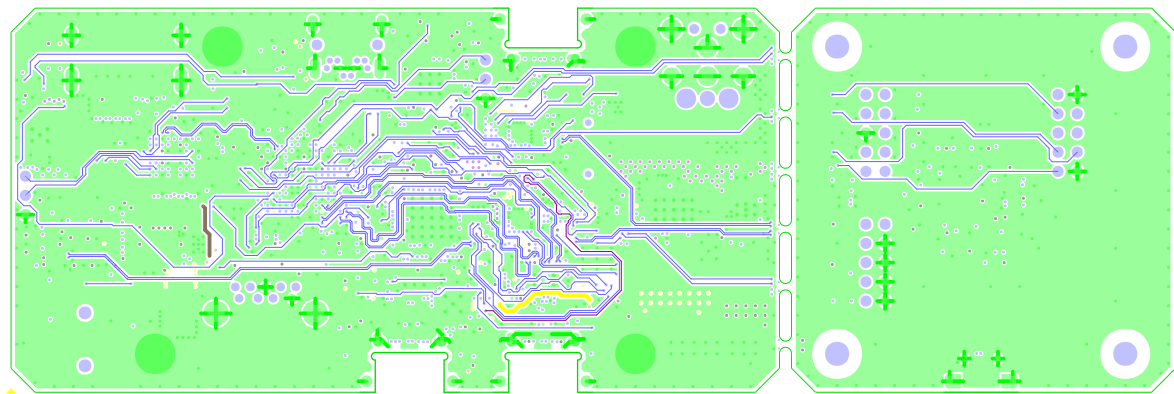
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 THIRD ANGLE PROJECTION TOLERANCES UNLESS OTHERWISE SPECIFIED UNITS IN (MM) IN (.XX)/-0.01 (.XXX)/-0.003 MM (.XX)/-0.01 (.XXX)/-0.003 FRACTION +/- 1/32 ANGLE +/- 1.0 DEGREE	CUSTOMER TEXAS INSTRUMENTS	ENGINEER J. ONTIVEROS
	BOARD NAME : USB TYPE C DOCK	
FABRICATION DRAWING		
APPROVALS	DATE	SIZE
DRAWN: MT	03-09-16	D
RELEASED: JO	03-09-16	16871
DO NOT SCALE DRAWING	SCALE NONE	SHEET 1 OF 1

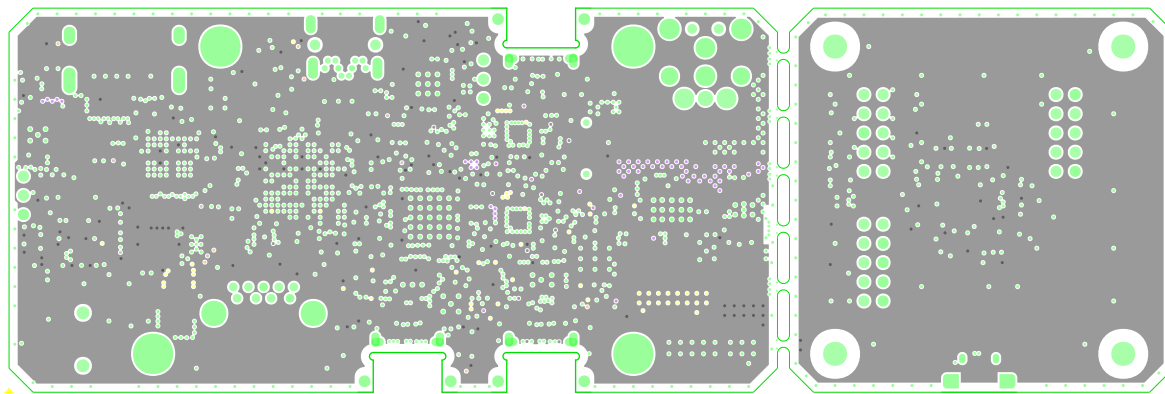
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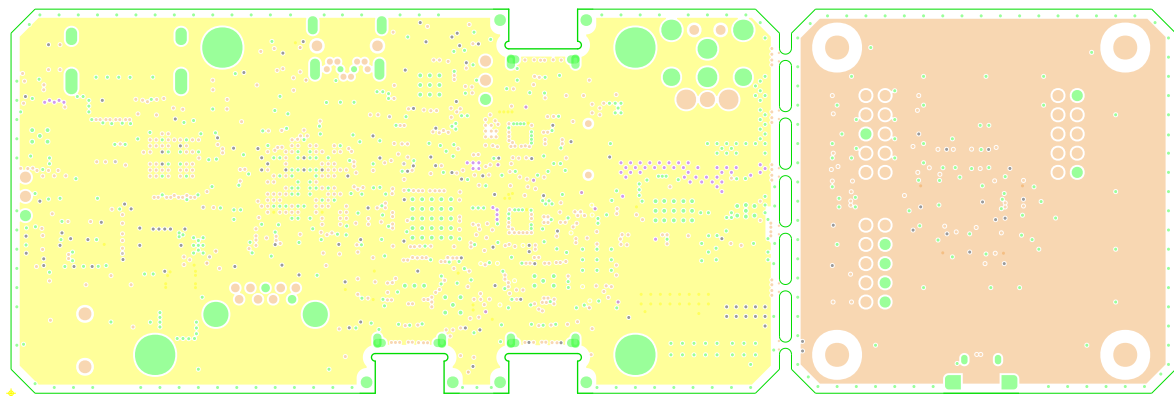
BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: LAYER 2 - GND PLANE	



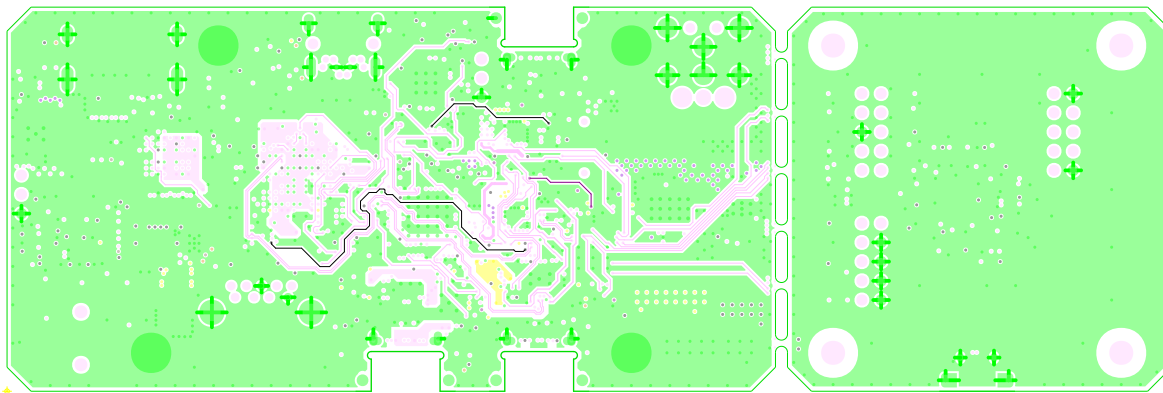
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ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 3 - SIG		



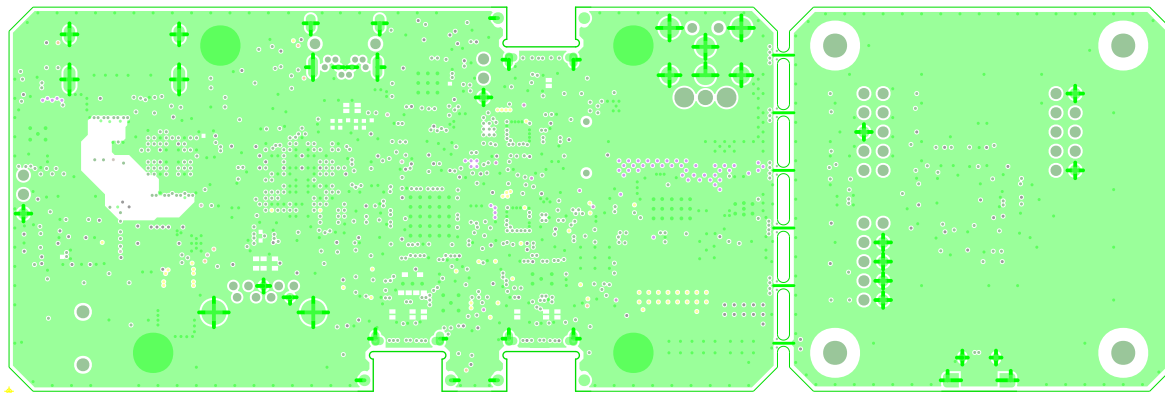
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ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 4 - 3P3V		



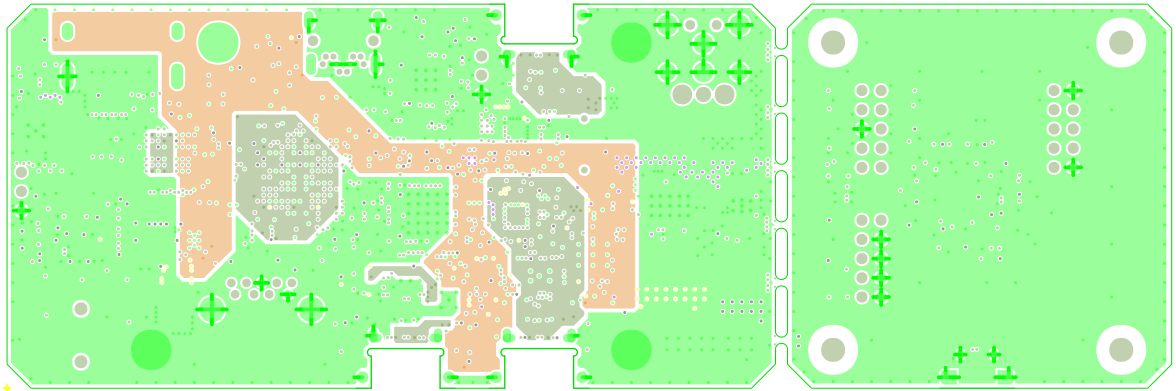
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ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 5 - PWR		



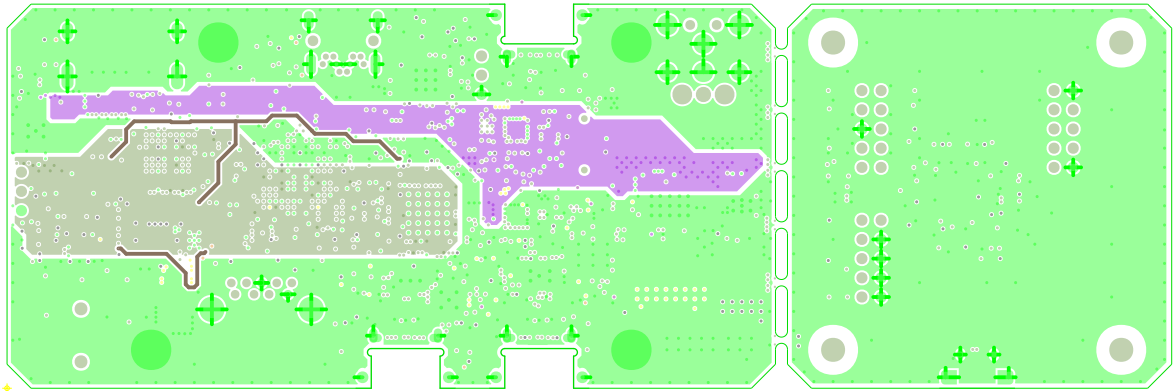
BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 8 - SIG		



BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: LAYER 9 - GND PLANE	



BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION:	



BOARD NAME: USB TYPE C DOCK	BOARD REV: 3.0	KSID: 16871	JOB NUMBER: 129072
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION:	

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